Reference

EMIFIL (Three-terminal capacitor)

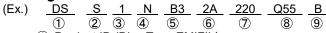
DSS1NB3

Reference Specification

1. Scope

This reference specification applies to DSS1NB3 series.

2. Part Numbering



- 1 Product ID (Disc-Type EMIFIL)
- 2 Structure S: Built-in Ferrite Beads Type
- 3 Style4 Features
- ⑤ Temperature Characteristics B3:±10% (-40~+85°C at 20°C)
- ⑥ Rated Voltage 2A :2A→100VDC、1H→50VDC
- ⑦ Capacitance

Marked three digits system.(Ex. 22pF→220、22000pF→223)

8 Lead Type

Q55 : Bulk

Lead Type :Straight Lead

Lead Length(I) 25.0 mm min. %See item 9.

Q91□: Taping

Lead Type: Straight Lead

Q91: $20.0 \pm 1.0 \text{ mm}$ Dimension H:

 $Q92:16.5\!\pm\!1.0\;mm$

Q93 : $18.5 \pm 1.0 \text{ mm}$ %See item 9.

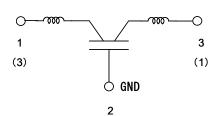
A: Ammo Pack / B: Bulk Packaging Code

3. Rating

Operating temperature : -40 to +85°C Storage Temperature : -40 to +85°C Insulation Resistance : $1000M\Omega$ min.

Rated Current : 6A(DC)

Equivalent Circuit :



Others: See Table 1

Table 1

Customer Part Number	Murata Part Number	Capacitance	Temperature Characteristics		Withstanding Voltage	Unit Mass (Typical value)
	DSS1NB32A220Q55B DSS1NB32A220Q91A DSS1NB32A220Q92A DSS1NB32A220Q93A	22 pF±10% 33 pF±10% 47 pF±10%	±10%	100VDC	250VDC	0.45g
	DSS1NB32A330Q55B DSS1NB32A330Q91A DSS1NB32A330Q92A DSS1NB32A330Q93A					
	DSS1NB32A470Q55B DSS1NB32A470Q91A DSS1NB32A470Q92A DSS1NB32A470Q93A					

Reference Only P2/9

Customer	Murata	Capacitance	Temperature	Rated	Withstanding	Unit Mass (Typical
Part Number	Part Number	Capacitance	Characteristics	Voltage	Voltage	value)
	DSS1NB32A680Q55B					value)
	DSS1NB32A680Q91A	00 5 400/				
·····	DSS1NB32A680Q92A	68 pF±10%				
·	DSS1NB32A680Q93A					
	DSS1NB32A101Q55B					
	DSS1NB32A101Q91A	100 pF±10%				
	DSS1NB32A101Q92A	100 pr ± 10%				
	DSS1NB32A101Q93A					
	DSS1NB32A121Q55B					
	DSS1NB32A121Q91A	120 pF±10%				
	DSS1NB32A121Q92A	0 p0%				
	DSS1NB32A121Q93A		-			
	DSS1NB32A151Q55B					
	DSS1NB32A151Q91A	150 pF±10%				
	DSS1NB32A151Q92A	·				
	DSS1NB32A151Q93A					
	DSS1NB32A221Q55B					
	DSS1NB32A221Q91A	220 pF±10%				
	DSS1NB32A221Q92A					
	DSS1NB32A221Q93A DSS1NB32A271Q55B		-			0.45g
	DSS1NB32A271Q55B	270 pF±10%				
	DSS1NB32A271Q91A					
	DSS1NB32A271Q93A DSS1NB32A331Q55B					
	DSS1NB32A331Q91A	-	±10%	100VDC	250VDC	
	DSS1NB32A331Q92A	330 pF±10%				
	DSS1NB32A331Q93A	470 pF±10%				
	DSS1NB32A471Q55B					
	DSS1NB32A471Q91A					
	DSS1NB32A471Q92A					
	DSS1NB32A471Q93A					
	DSS1NB32A681Q55B					
	DSS1NB32A681Q91A	680 pF±10%				
	DSS1NB32A681Q92A	000 pt = 1070				
	DSS1NB32A681Q93A					
	DSS1NB32A102Q55B					
	DSS1NB32A102Q91A	1000 pF±10%				
	DSS1NB32A102Q92A DSS1NB32A102Q93A					
	DSS1NB32A152Q55B		-			
	DSS1NB32A152Q91A					
	DSS1NB32A152Q92A	1500 pF±10%				
	DSS1NB32A152Q93A					
	DSS1NB32A222Q55B	2200 pF±10%				
	DSS1NB32A222Q91A					
	DSS1NB32A222Q92A					
	DSS1NB32A222Q93A					
	DSS1NB32A332Q55B					
	DSS1NB32A332Q91A	3300 pF±10%				
	DSS1NB32A332Q92A	- 1070				
	DSS1NB32A332Q93A					
	DSS1NB32A472Q55B					
	DSS1NB32A472Q91A	4700 pF±10%				
	DSS1NB32A472Q92A					
	DSS1NB32A472Q93A				<u> </u>	

Reference Only

Customer Part Number	Murata Part Number	Capacitance	Temperature Characteristics	Rated Voltage	Withstanding Voltage	Unit Mass (Typical value)
	DSS1NB32A682Q55B DSS1NB32A682Q91A DSS1NB32A682Q92A DSS1NB32A682Q93A	6800 pF±10%		100VDC	250VDC	
	DSS1NB32A103Q55B DSS1NB32A103Q91A DSS1NB32A103Q92A DSS1NB32A103Q93A	10000 pF±10%				0.45g
	DSS1NB32A153Q55B DSS1NB32A153Q91A DSS1NB32A153Q92A DSS1NB32A153Q93A	15000 pF±10%	±10%			
	DSS1NB32A223Q55B DSS1NB32A223Q91A DSS1NB32A223Q92A DSS1NB32A223Q93A	22000 pF±10%				
	DSS1NB31H333Q55B DSS1NB31H333Q91A DSS1NB31H333Q92A DSS1NB31H333Q93A	33000 pF±10%			125VDC	
	DSS1NB31H473Q55B DSS1NB31H473Q91A DSS1NB31H473Q92A DSS1NB31H473Q93A	47000 pF±10%				
	DSS1NB31H104Q55B DSS1NB31H104Q91A DSS1NB31H104Q92A DSS1NB31H104Q93A	100000pF± 10 %				

4. Style and Dimension

See item 9.

5. Marking

Trade Mark : Marked as

Capacitance : Marked three digits system. (Ex.221)
Rated Voltage : Marked voltage value.(100V)

6. Testing Conditions

<Unless otherwise specified><In case of doubt>

Temperature : Ordinary Temperature 15 to 35°C Perform a heat treatment at 150+0/-10°C for one hour Humidity : Ordinary Humidity 25 to 85 %(RH) and then set at room temperature for 24±2 hours.

Temperature : 20 ± 2°C Humidity : 60 to 70 %(RH) Atmospheric Pressure : 86 to 106 kPa

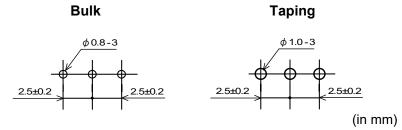
7. Performance

<u> </u>	TOTTILATICE				
No.	Item	Specification	Test Method		
7.1	Appearance and Dimensions	Meet item 9.	Visual Inspection and measured with Slide Calipers.		
7.2	Marking	Marking is able to be read easily.	Visual Inspection.		
7.3	Capacitance and	Meet item 3.	Table 2		
	Tolerance		Frequency Test Voltage Capacitance		
			1±0.1MHz 1±0.2Vrms 22pF~150pF		
			1±0.1kHz 1±0.2Vrms 220pF~100000pF		
7.4	Insulation	Meet item 3.	Test Voltage : Rated Voltage		
	Resistance(I.R.)		Time : 1 minute through a suitable resistor $1M\Omega$.		

Reference Only P4/9

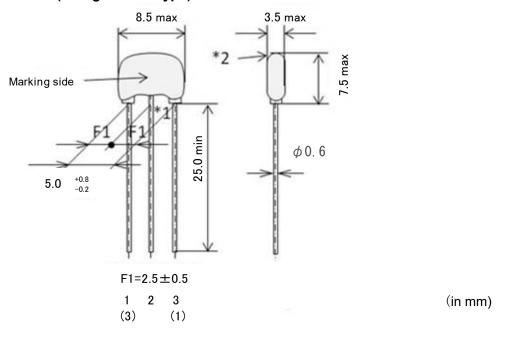
No.	Item	Spe	ecification	Test Method		
7.5	Withstanding	Products shall not be damaged.		Test Voltage : 2.5 times for Rated Voltage		
	Voltage	, and the second		Time: 1 to 5 seconds		
	3			Charge Current : 10 mA max. It shall be applied between input / output terminal		
				and ground terminal.		
7.6	Temperature	Meet item 3.		Capacitance shall be measured at each step specified in Table 3 after reaching the thermal equilibrium.		
	Characteristics					
				The capacitance change against the capacitance a		
				step 3 shall be calculated.		
				Table3		
				Step 1 2 3 4 5		
				Temp. $ +20\pm2 +40\pm2 +20\pm2 +85\pm2 +20\pm2 $		
				(°C)		
7.7	Solderability	Along the circumfe		Flux : Ethanol solution of rosin,25(wt)%		
		shall be covered	with new solder a	[] []		
		75%.		Pre-heat: 150±10°C, 60~90 s		
				Solder: Sn-3.0Ag-0.5Cu		
				Solder Temperature 245±5°C Immersion Time: 2 ± 0.5 seconds		
				Immersion Depth :		
				2 to 2.5 mm from the bottom of the body.		
7.8	Resistance to	Meet Table 4.		Flux : Ethanol solution of rosin,25(wt)%		
	Soldering Heat①	Table 4		(dipped for 5 to 10 seconds)		
	o o	Appearance	No damaged.	Pre-heat : 150±10°C, 60~90 s		
		Capacitance		Solder : Sn-3.0Ag-0.5Cu		
		Change	within ± 30%	Solder Temperature : 270 ± 5 °C		
		Withstanding	No damaged.	Immersion Time : 3± 0.5 seconds		
		Voltage	110 damagod.	Immersion Depth:		
				1.6 ± 0.7 mm from the bottom of the body. Then measured after exposure in the room		
				condition for 4 to 24hours.		
	Resistance to			Soldering iron output: 30W		
	Soldering Heat②			Tip temperature : 370±10°C		
				Soldering time : 5s(+0/-1s)		
7.9	Humidity	Meet Table 5.		Temperature : 60°C		
	,	Table 5		Humidity : 90 to 95 %(RH)		
				Time : 500 hours(+24-0 hours)		
		Appearance	No damaged.	Then measured after exposure in the room		
		Capacitance	within ± 30%	condition for 4 to 24hours.		
7.10	Humidity Life	Change		Temperature : 40 ± 2°C		
	Inslation		40040 :	Humidity: 90 to 95 %(RH)		
		Resistance	10MΩ min.	Time : 500 hours(+24-0 hours)		
				Applying Voltage : 1H/ Rated Voltage 50VDC		
1				2A/ Rated Voltage 100VDC		
				Then measured after exposure in the room		
<u> </u>		-		condition for 4 to 24hours.		
7.11	Heat Life			Temperature: 85 ± 3°C		
				Applying Voltage : 1H/ Rated Voltage 50VDC		
				2A/ Rated Voltage 100VDC		
				Time: 500 hours(+24-0 hours)		
				Then measured after exposure in the room condition for 4 to 24hours.		
Ь				CONDITION 4 to 24HOURS.		

8. Mounting Hole



9. Style and Dimension

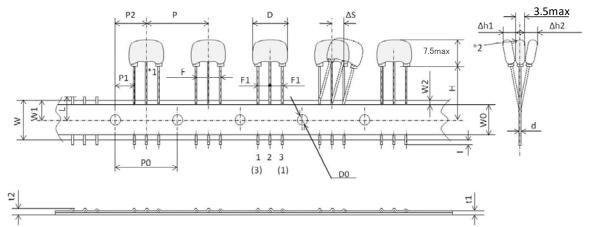
9.1 Bulk(Straight Lead Type): Q55B



- *1.Bottom of dielectric may be exposed.
- *2. There should not be the exposure of the ferrite bead if a hole is on the top of ferrite bead.

9.2 Taping(Straight Lead Type) : Q9 □ A

(All symbols in the illustrations below are described in Table 6)



^{*1.}Bottom of dielectric may be exposed.

Table 6

Code	Description		Dimensions	Remark
Р	Pitch of Component		12.7	Product Inclination
	Then of component		12.1	ΔS Determines Crossing
P ₀	Pitch of Sprocket Hole		12.7±0.2	
P1	Length from Hole Center to Lead		3.85±0.7	
P2	Length from Hole Center to Component Center		6.35±1.3	
D	Width of Body		8.5 max.	
ΔS	Deviation along tape, Left or Right		0±1.0	
W	Carrier Tape Width		18.0±0.5	
W1	Position of Sprocket Hole		9.0 +0,-0.5	Tape Widthwise Shift
Į	Protrusion Length		+0.5 ~ - 1.0	
D ₀	Diameter of Sprocket Hole		φ 4.0±0.1	
d	Lead Diameter	ф 0.6		
t1	Total Tape Thickness		0.7±0.2	Includes Thickness of
t2	Total Thickness,Tape and Lead Wire		1.5 max.	Bonding Tape
∆h1	Deviation across Tape,front	1.0 max.		
∆h2	Deviation across Tape,rear		1.0 max.	
L	Portion to Cut in Case of Defect		11.0 +0,-1.0	
W ₀	Hold Down Tape Width		12.0±0.5	
W2	Hold Down Tape Position	1.5±1.5		
		Q91	20.0±1.0	
Н	Lead length between sprocket hole and forming position	Q92	16.5±1.0	
		Q93	18.5±1.0	
F			5.0 +0.8,-0.2	
F1	Lead Spacing		2.5 +0.4,-0.2	

(in mm)

^{*2.} There should not be the exposure of the ferrite bead if a hole is on the top of ferrite bead.

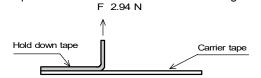
(in mm)

(in mm)

Reference Only

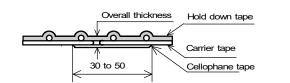
10. Taping

- (1) A maximum of 0.3% of the components quantity per Ammo pack may be missing without consecutive missing components.
- (2) The adhesive power of the tape shall have over 2.94N at the following condition.



- (3) Splicing method of tape
 - 1. Carrier tape

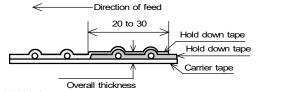
Carrier tape shall be spliced by cellophane tape.



2. Hold down tape

Hold down tape shall be spliced with overlapping.

Overall thickness shall be less than 1.05 mm.



3. Both carrier tape and hold down tape

Both tapes shall be cut zigzag and spliced with splicing tape.

11. Packing

11.1 Packing quantity

The standard packing quantity is as follows.

(The packing quantity may be changed due to a fraction of order.)

Minimun Packing Form and Quantity

<u> </u>						
Terminal Configuration	A Unit Quantity	Packing Form	Standard Quantity in a container (corrugated cardboard box)			
Bulk	250 pcs.	In a plastic bag	5000pcs.			
Taping	1500 pcs.	In an Ammo pack	7500pcs.			

^{*} A quantity in a container is depending on a quantity of an order.

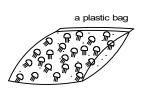
11.2 Packing Form

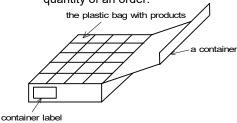
(1) Bulk

<A plastic bag pack>

1.Products are packed into a plastic bag.

2. The plastic bags are put into a container (corrugated cardboard box) depending on a quantity of an order.

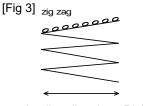


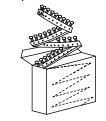


(2) Taping

<An ammo pack>

- 1 .Folding the tape per 25 pitches,products are packed into an ammo package so that each product of each layer wound zigzag is put on top of one another. [Fig 3]
- 2. The dimensions of the ammo package are indicated in [Fig 4].
- 3. The ammo packages are put into a container (corrugated cardboard box) depending on a quantity of an order.
- 4. Not less than 3 consecutive of component shall be missing on both edge of tape.





[Fig 4] 240 max. label 340 max. (in mm)

The unloading direction: Right The hold down tape: Upper

The product body: Left along the unloading direction

12. Marking on package

12.1 Unit Package

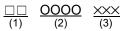
Bulk : Marked on a plastic bag.

Taping: Marked on a label stuck on an ammo package.

Marking on a unit package consists of :

Customer part number, MURATA part number, Inspection number(*1), RoHS marking (*2), Quantity, etc

*1) « Expression of Inspection No. »



(1) Factory Code (2) Date

First digit : Year / Last digit of year

Second digit : Month / Jan. to Sep. \rightarrow 1 to 9, Oct. to Dec. \rightarrow O,N,D

Third, Fourth digit: Day

(3) Serial No.

*2) « Expression of RoHS marking »

ROHS $-\frac{Y}{(1)}(\triangle)$

- (1) RoHS regulation conformity parts.
- (2) MURATA classification number

12.2 Container

Marking on the label stuck on a container consists of :

Customer name Purchasing Order Number, Customer Part Number, MURATA part number,

RoHS marking (*2), Quantity, etc

13. \triangle Caution

13.1 Mounting holes

Mounting holes should be designed as specified in this specifications.

Or different design from this specifications may cause cracks in ceramics which may lead to smoking / firing.

13.2 Caution for the product angle adjust work

Take care not to apply any mechanical stress to product body at the lead terminal bending process for product angle adjustment after insertion.

13.3 Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

(1) Aircraft equipment

(7) Traffic signal equipment

(2) Aerospace equipment

(7) Disaster prevention / crime prevention equipment

(3) Undersea equipment

(9) Data-processing equipment

(4) Power plant control equipment

(10) Applications of similar complexity and /or reliability requirements

(5) Medical equipment

to the applications listed in the above

(6) Transportation equipment (vehicles, trains, ships, etc.)

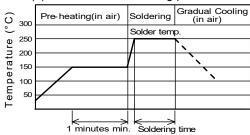
14. Notice

14.1 Soldering

(1) Use rosin-based flux. Do not use strong acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).

Use Sn-3.0Ag-0.5Cu solder

(2) Standard flow soldering profile.



Solder	Soldering
temperature	time
250~260 °C	4~6s

- (3) Resistance to soldering iron goes in the following condition that tip temperature is 350 °C max. And soldering time is 5 s max.
- (4) Products and the leads should not be subjected to any mechanical stress during soldering process. (and also while subjected to the equivalent high temperature.)

14.2 Cleaning

Products shall be cleaned on following conditions.

- (1) Cleaning Temperature: 60°C max.(40°C max. for Isopropyl alcohol).
- (2) Ultrasonic cleaning shall comply with the following conditions, avoiding the resonance phenomenon at the mounted products and P.C.B.

Power: 20W / I max. Frequency: 28kHz ~ 40kHz Time: 5 minutes max.

- (3) Cleaning agent
 - 1. alcohol cleaning agents.
 - · Isopropyl alcohol (IPA)
 - 2. Aqueous cleaning agent
 - · Pine Alpha ST-100S
- (4) Ensure that residual flux and residual cleaning agent is completely removed.

Products should be thoroughly dried after aqueous agent has been removed with de-ionized water.

(5) For other cleaning methods, please contact Murata engineering.

14.3 Operating Environment

- (1) Do not use products in corrosive gases such as chlorine gas, acid or sulfide gas.
- (2) Do not use products in the environment where water, oil or organic solvents may adhere to products.
- (3) Do not adhere any resin to products, coat nor mold products with any resin (including adhesive)to prevent mechanical and chemical stress on products.

14.4 Storage and handling requirements.

(1) Storage period

Use the products within 12 months after delivered.

Solderability should be checked if this period is exceeded.

(2) Storage environment condition

To prevent products quality deterioration, stored conditions should be controlled as follows;

- 1. Temperature : -10 to 40 degrees centigrade
- 2. Humidity : 15 to 85% relative humidity
- Products should be stored without sudden changes in temperature and humidity. Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of lead terminals resulting in poor solderability.
- 4. Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- 5. Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
- (3) Handling Conditions

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

15. **A** Note

- (1)Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2)You are requested not to use our product deviating from the reference specifications.
- (3)The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering.